



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 520 H6327		<b>Issued</b>		26. January 2016		
<b>MA#</b>		MA000808534						
<b>Package</b>		PG-SOT343-4-2		<b>Weight*</b>		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		281	
	non noble metal	tin	7440-31-5	0.001	0.01		72	
	inorganic material	silicon	7440-21-3	0.014	0.21	0.25	2081	2434
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.55	49.76	495530	497621
wire	noble metal	gold	7440-57-5	0.010	0.14	0.14	1432	1432
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4382	
	plastics	epoxy resin	-	0.653	9.42		94209	
	inorganic material	silicondioxide	60676-86-0	2.353	33.96	43.82	339591	438182
leadfinish	non noble metal	tin	7440-31-5	0.202	2.91	2.91	29116	29116
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31215	31215
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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